



NOTES

1. FINISH : GOLD PLATED 60 MICRO INCHES MIN. THICKNESS OVER NICKEL PLATED.
2. NO PIN CONNECTED TO DIE ATTACH PAD. (GROUND)

MODIFICATIONS						NAME	40 LEAD CERAMIC CHIP CARRIER	TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1% N.L.T. ±.005 THIRD ANGLE PROJECTION	DRAWN	CHECKED	APPROVED	DATE	S=0 BSS-40 D=0
						SCALE	8 / 1		MATERIAL	AS INDICATED	S.M	UE. K.H	
	CHANGE		DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. PB-12836			SHEET /	